


Notes:

1. All dimensions are in mm. Angles in degrees.
2. Coplanarity applies to the exposed pad as well as the terminals.
3. Refer JEDEC MO-229
4. Thermal pad soldering area (mesh stencil design is recommended)

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|  PERICOM <i>Enabling Serial Connectivity</i> | DATE: 09/20/10 |
| DESCRIPTION: 8-contact, Thin Dual-in-Line Flat Package (TDFN) | |
| PACKAGE CODE: ZA8 | |
| DOCUMENT CONTROL #: PD-2068 | REVISION: B |